

Features

- Industry standard PLCC-2 package.
- High reliability LED Package
- Inter reflector.
- Available in full selection of colors.
- Suitable for automatic placement equipment.
- Suitable for vaporphase reflow, Infrared reflow and wave solder processes.
- The product itself will remain RoHS compliant.

RS PRO LEDs

RS Stock No.: 0588777



RS PRO is the own brand of RS. The RS PRO Seal of Approval is your assurance of professional quality, a guarantee that every part is rigorously tested, inspected, and audited against demanding standards. Making RS PRO the Smart Choice for our customers.



Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the SMT TOP LED ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

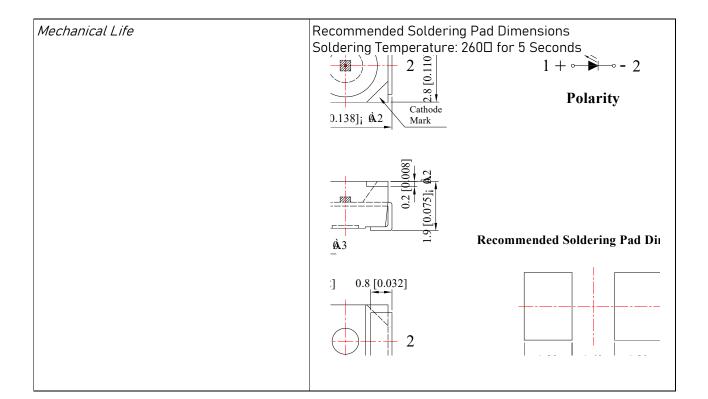
- Instrument panel backlighting
- Central console backlighting
- Switch push button backlighting
- Electronic signs and signals
- Office automation,home appliances,industrial equipment
- Front panel backlighting
- Push button backlighting
- Display backlighting
- Light pipe application

General Specifications

LED Colour	Warm White, SMD LED
Dimensions	3.5x 2.8mm, Surface Mount Chip LED Indicator

Mechanical Specifications







Parameters	Symbol	Max	Unit
Power Dissipation	Pd	90	mW
Peak Forward Current ^(a)	IFP	100	mA
DC Forward Current	IF	25	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	1000	V
Operating Temperature Range	Topr	-40□ to+85□	
Storage Temperature Range	Tstg	-40□ to+85□	
Soldering Temperature	Tstg	260□for 5 Seconds	

Notes:

a.Duty Factor = 10%, Frequency = 1 kHz

Electrical Optical Characteristics at Ta=25 ℃

Parameters	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Flux ^(a)	Ф٧	7	8		LM	IF=20mA
Viewing Angle	201/2		120		Deg	IF=20mA
	Х		0.43		nm	IF=20mA
Chromaticity Coordinates (b)	Y		0.40		nm	IF=20mA
Color Temperature	CCT	2600	3000	3500	K	IF=20mA
Forward Voltage ^(c)	VF	2.60	3.20	3.60	V	IF=20mA
Reverse Current	IR			10	μΑ	VR=5V

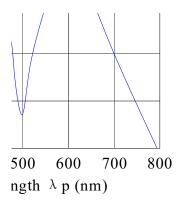
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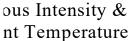
- a. Luminous flux measurement tolerance: ±10%.
- b. Color coordinates measurement tolerance: ±0.015
- c. Forward voltage measurement tolerance: ±0.1V

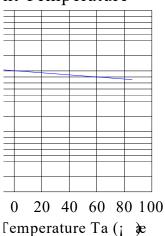
Typica IElectrical / Optical Characteristics Curves

(25℃ Ambient Temperature Unless Otherwise Noted)

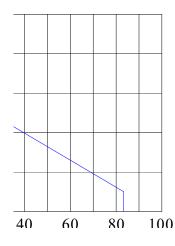


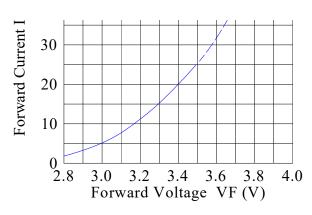




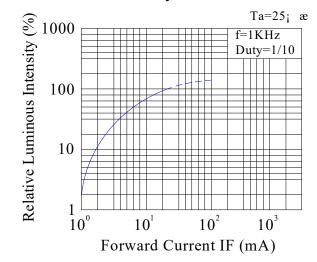


rrent Derating Curve

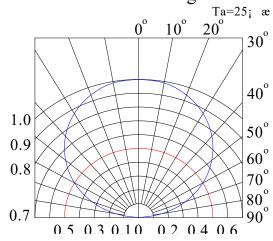




Luminous Intensity & Forward Current

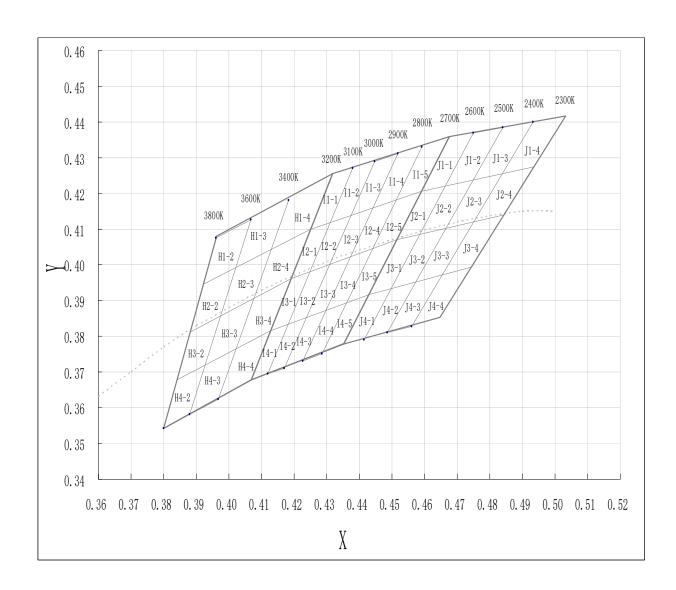


Radiation Diagram



CIE 1931 Chromaticity Diagram





Chromaticity Coordinates Specifications for Bin Rank



Bin Code	Left x	Left y	Тор х	Тор у	Right x	Right y	Bottom x	Bottom y
H1-2	0.392	0.394	0.402	0.399	0.407	0.413	0.396	0.408
H2-2	0.388	0.381	0.397	0.386	0.402	0.399	0.392	0.394
H3-2	0.384	0.367	0.393	0.372	0.397	0.386	0.388	0.381
H4-2	0.380	0.354	0.388	0.358	0.393	0.372	0.384	0.367
H1-3	0.402	0.399	0.412	0.403	0.418	0.419	0.407	0.413
H2-3	0.397	0.386	0.407	0.390	0.412	0.403	0.402	0.399
H3-3	0.393	0.372	0.402	0.376	0.407	0.390	0.397	0.386
H4-3	0.388	0.358	0.397	0.362	0.402	0.376	0.393	0.372
H1-4	0.412	0.403	0.425	0.410	0.432	0.426	0.418	0.419
H2-4	0.407	0.390	0.419	0.396	0.425	0.410	0.412	0.403
H3-4	0.402	0.376	0.413	0.382	0.419	0.396	0.407	0.390
H4-4	0.397	0.362	0.407	0.368	0.413	0.382	0.402	0.376
I1-1	0.425	0.410	0.431	0.412	0.438	0.428	0.432	0.426
I2-1	0.419	0.396	0.424	0.398	0.431	0.412	0.425	0.410
I3-1	0.413	0.382	0.418	0.384	0.424	0.398	0.419	0.396
I4-1	0.407	0.368	0.412	0.370	0.418	0.384	0.413	0.382
I1-2	0.431	0.412	0.437	0.414	0.445	0.430	0.438	0.428
12-2	0.424	0.398	0.430	0.400	0.437	0.414	0.431	0.412
13-2	0.418	0.384	0.423	0.385	0.430	0.400	0.424	0.398
14-2	0.412	0.370	0.417	0.372	0.423	0.385	0.418	0.384
I1-3	0.437	0.414	0.444	0.416	0.452	0.432	0.445	0.430
12-3	0.430	0.400	0.437	0.402	0.444	0.416	0.437	0.414
13-3	0.423	0.385	0.430	0.387	0.437	0.402	0.430	0.400
14-3	0.417	0.372	0.423	0.374	0.430	0.387	0.423	0.385
I1-4	0.444	0.416	0.451	0.418	0.459	0.434	0.452	0.432
12-4	0.437	0.402	0.444	0.404	0.451	0.418	0.444	0.416
13-4	0.430	0.387	0.436	0.389	0.444	0.404	0.437	0.402
14-4	0.423	0.374	0.429	0.376	0.436	0.389	0.430	0.387

	11 5	0.451	0.418	0.460	0.421	0.468	0.436	0.459	0.434
	11-5	0.431	0.410	0.400	0.421	0.400	0.430	0.439	0.434
L									



12-5	0.444	0.404	0.452	0.407	0.460	0.421	0.451	0.418
13-5	0.436	0.389	0.444	0.392	0.452	0.407	0.444	0.404
14-5	0.429	0.376	0.436	0.378	0.444	0.392	0.436	0.389
J1-1	0.460	0.421	0.466	0.422	0.475	0.437	0.468	0.436
J2-1	0.452	0.407	0.458	0.408	0.466	0.422	0.460	0.421
J3-1	0.444	0.392	0.449	0.393	0.458	0.408	0.452	0.407
J4-1	0.436	0.378	0.441	0.379	0.449	0.393	0.444	0.392
J1-2	0.466	0.422	0.475	0.424	0.484	0.439	0.475	0.437
J2-2	0.458	0.408	0.467	0.410	0.475	0.424	0.466	0.422
J3-2	0.449	0.393	0.458	0.395	0.467	0.410	0.458	0.408
J4-2	0.441	0.379	0.449	0.381	0.458	0.395	0.449	0.393
J1-3	0.475	0.424	0.483	0.425	0.493	0.440	0.484	0.439
J2-3	0.467	0.410	0.475	0.412	0.483	0.425	0.475	0.424
J3-3	0.458	0.395	0.465	0.397	0.475	0.412	0.467	0.410
J4-3	0.449	0.381	0.456	0.383	0.465	0.397	0.458	0.395
J1-4	0.483	0.425	0.493	0.427	0.503	0.442	0.493	0.440
J2-4	0.475	0.412	0.484	0.414	0.493	0.427	0.483	0.425
J3-4	0.465	0.397	0.474	0.399	0.484	0.414	0.475	0.412
J4-4	0.456	0.383	0.465	0.385	0.474	0.399	0.465	0.397

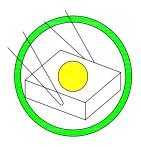
Notes:

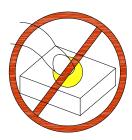
1. Color coordinates measurement allowance is ± 0.015.

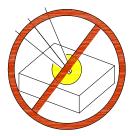


1. Handling Precautions:

- 1.1 Handle the component along the side surfaces by using forceps or appropriate tools.
- 1.2 Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.
- 1.3 Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.









1.4 compared to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

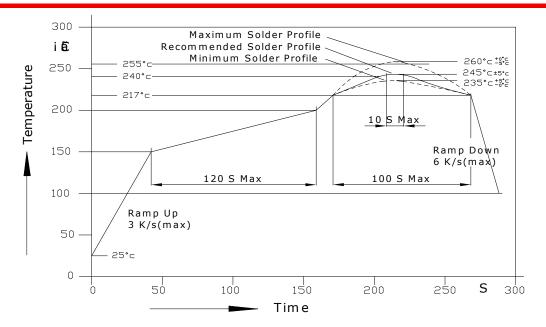
2. Storage:

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.5 The LEDs should be used within 24 hours after opening the package.
- 2.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 65±5°C for 24 hours.

3. Soldering Condition:

3.1 Pb-free solder temperature profile.





- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
- 3.5 Recommended soldering conditions:

Reflo	w soldering	Soldering iron			
Pre-heat	150~200°C	Temperature	300°C Max.		
Pre-heat time	120 sec. Max.	Soldering time	3 sec. Max.		
Peak temperature	260°C Max.		(one time only)		
Soldering time	10 sec. Max. (Max. two times)				

3.6 Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations.

However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

4. Drive Method:

4.1 An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.

Circuit model A Circuit model B

LED LED





- (A) Recommended circuit.
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

5. ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- ullet All devices, equipment, and machinery must be properly grounded. \Box
- ullet Work tables, storage racks, etc. should be properly grounded. \Box
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's
 plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents. To verify for ESD damage, check for "lightup" and Vf of the suspect LEDs at low currents. The Vf of "good" LEDs should be >2.0V@0.1mA for InGaN product and >1.4V@0.1mA for AlInGaP product.

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